



Click [here](#) for the 3D model.

| Dimensions |                 |
|------------|-----------------|
| L          | 1.6mm +/-0.2mm  |
| W          | 3.2mm +/-0.2mm  |
| T          | 0.8mm +/-0.10mm |
| P          | 0.8mm +/-0.10mm |

| Packaging Specifications |                        |
|--------------------------|------------------------|
| Packaging                | T&R, 180mm, Paper Tape |
| Packaging Quantity       | 4000                   |

| General Information      |  |
|--------------------------|--|
| Series                   | Array Comm COG Flex                          |
| Style                    | SMD Array                                    |
| Description              | SMD, MLCC, Array, Flex Termination, Class II |
| RoHS                     | Yes  |
| Termination              | Flexible Termination                         |
| AEC-Q200                 | No   |
| Typical Component Weight | 18 mg  |
| Notes                    | Last Time Buy Date (LTB): May 30th, 2024.    |
| Chip Size                | 0612   |
| Shelf Life               | 78 Weeks                                     |
| MSL                      | 1  |

| Specifications   |                        |
|--|------------------------|
| Capacitance  | 22 pF                  |
| Measurement Condition  | 1MHz 1.0Vrms           |
| Capacitance Tolerance  | 10%                    |
| Voltage DC   | 25 VDC                 |
| Dielectric Withstanding Voltage                                    | 62.5 VDC               |
| Temperature Range  | -55/+125°C             |
| Temperature Coefficient  | COG                    |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1MHz 1.0Vrms |
| Dissipation Factor   | 0.1% 1MHz 1.0Vrms      |
| Aging Rate   | 0% Loss/Decade Hour    |
| Insulation Resistance  | 100 GOhms              |